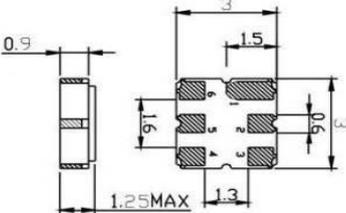


# Specification Sheet

Customer Name	XXXX	CUST P/N	NA
Approval No.	PD	Temwell P/N	STSF-2605B60-S3030W
Lot No.		Date	2025.06.24
Description	SAW Filter (BandPass)	Version	A1

### (1) Size Diagram (Unit : MM)



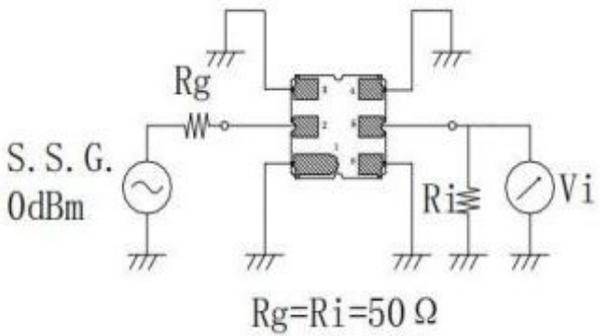
PinNo.	Description
2	Input
5	Output
1,3,4,6	Ground
Tolerance	±0.1mm

### (2) Electrical Specifications

Item			Specification		
Parameter	MHz	Unit	Min.	Typical	Max.
Center Frequency	-	MHz	-	2605	-
Insertion Loss	2605	dB	-	2.0	2.5
Insertion Loss	2575-2635	dB	-	2.8	4.0
Ripple	2575-2635	dB	-	0.9	2.5
Group Delay	2575-2635	ns	-	10	30
Attenuation	DC-2525	dB	30	35	-
	2525-2555	dB	3	6	-
	2645-2655	dB	1	2	-
	2655-2695	dB	3	10	-
	2695-4000	dB	25	30	-
VSWR	2575-2635	-	-	1.6:1	2.0:1
Operation Temperature	-40°C~+85°C	°C	-	-	-
Storage Temperature	-40°C~+125°C	°C	-	-	-
RF Power Dissipation	20	dBm	-	-	-

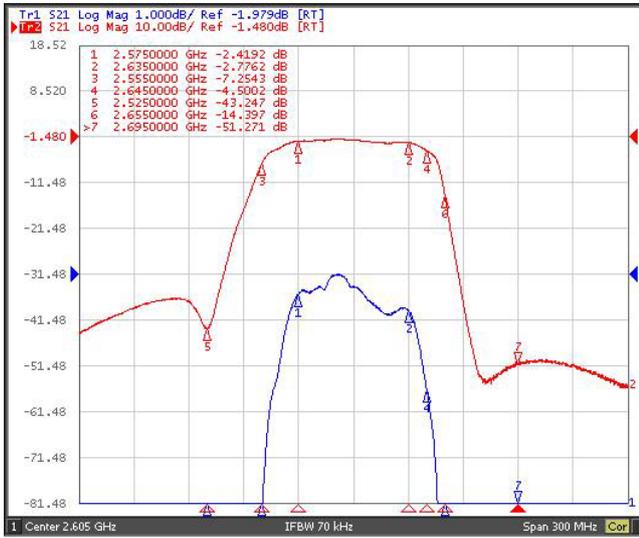
Remark: Note 1: Test Temperature: 25°C±2°C  
 Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω

### (3) Test Circuit

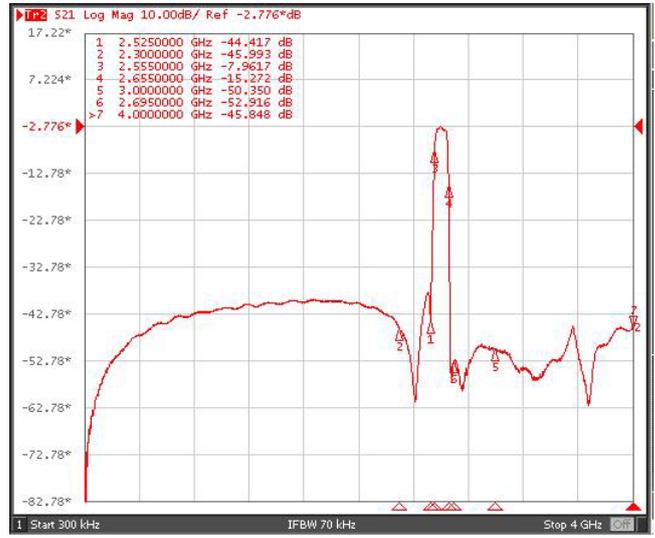


Port	Matching component
Input	R1: 50Ω
Output	R2: 50Ω

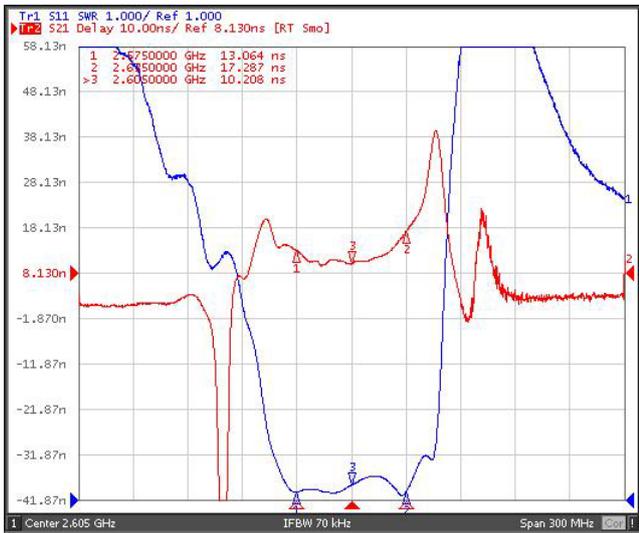
**Figure 1. Electrical Characteristics: Frequency response**



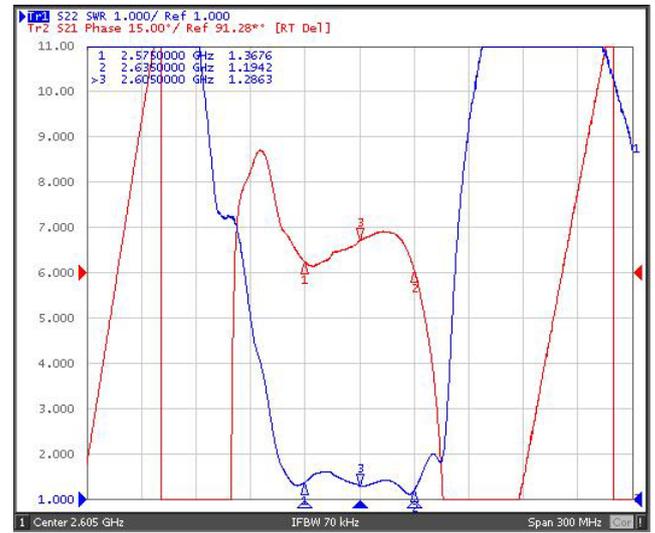
**Figure 2. Electrical Characteristics: Wideband**



**Figure 3. Delay Ripple & S11 VSWR**

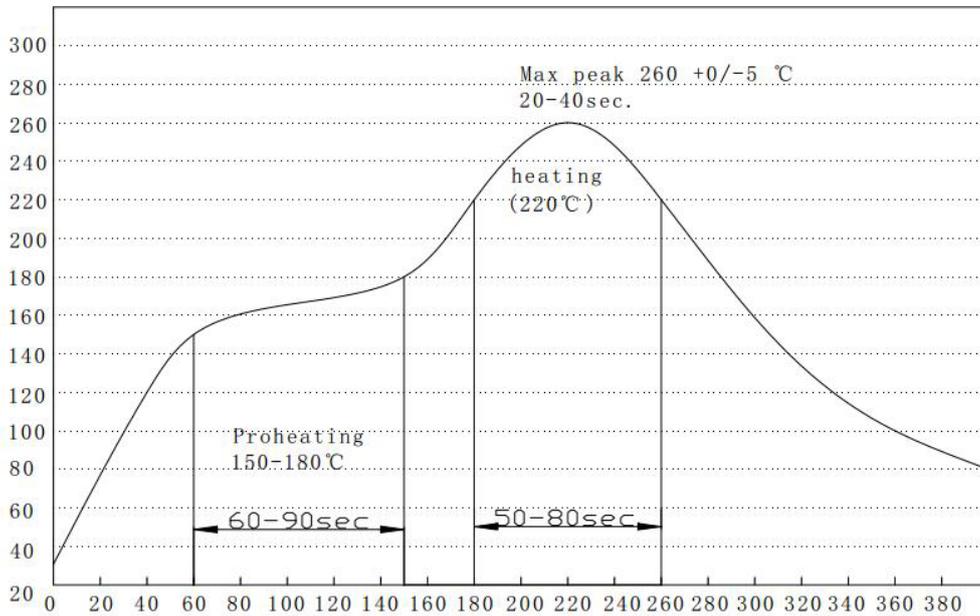


**Figure 4. Phase Linearity & S22 VSWR**



Approval	Supervisor	Designer
C. K. Chang	M. Y. Chen	F.L.Lai

## Recommended SMT Solder Profile



## Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85°C $\pm$ 2°C , Duration: 250h , Recovery time: 2h $\pm$ 0.5h Temperature: -40°C $\pm$ 3°C , Duration: 250h ,Recovery time: 2h $\pm$ 0.5h	
2	Humidity Test	Conditions: 60°C $\pm$ 2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C $\pm$ 3°C, TB=85°C $\pm$ 2°C, t1=t2=30min, Switch time: $\leq$ 3min, Cycle time: 100 times, Recovery time: 2h $\pm$ 0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height: 1.0m
6	Solder Ability Test	Temperature:245°C $\pm$ 5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C $\pm$ 5°C , Duration:10 $\pm$ 1s Temperature of Soldering Iron: 350°C $\pm$ 10°C, Duration: 3~4s, Recovery time : 2 $\pm$ 0.5h	